

AMENDMENTS TO THE CLAIMS

Please **CANCEL** claims 10, 14 and 15 without prejudice or disclaimer.

Please **AMEND** claims 1, 12 and 13 as shown below.

Please **ADD** claim 21 as shown below.

The following is a complete list of all claims in this application.

WHAT IS CLAIMED IS:

1. (currently amended) A system of manufacturing a liquid crystal display, the system comprising:

a panel manufacturing unit for manufacturing a liquid crystal panel assembly including a thin film transistor (TFT) array panel, a color filter array panel, and a liquid crystal layer interposed between the TFT array panel and the color filter array panel;

a printed circuit film bonding unit for bonding a printed circuit film on the panel assembly;

a printed circuit board (PCB) bonding unit for bonding a PCB to the printed circuit film; and

an inspection unit for inspecting the bonding of the printed circuit film on the panel assembly, wherein the bonding inspection unit comprises two sub-units for inspection before and after the bonding of the PCB, respectively.

2. (original) The system of claim 1, wherein the printed circuit film comprises a tape carrier package.

3. (original) The system of claim 1, wherein the inspection unit comprises a differential camera or a differential scope.

4. (original) The system of claim 1, wherein the printed circuit film bonding unit bonds the printed circuit film on the panel assembly with an anisotropic conductive film (ACF).

5. (original) The system of claim 4, wherein the ACF comprises an adhesive containing a plurality of conductive particles.

6. (original) The system of claim 5, wherein the printed circuit film bonding unit bonds the printed circuit film on the panel assembly by compression.

7. (original) The system of claim 6, wherein the inspection unit detects dents generated by the compression.

8. (original) The system of claim 1, wherein the inspection unit detects alignment of the printed circuit film with the panel assembly.

9. (original) The system of claim 1, wherein the bonding inspection unit is incorporated into the printed circuit film bonding unit or the PCB bonding unit.

10. (canceled)

11. (currently amended) The system of claim ~~10~~ 1, wherein one of the sub-units of the bonding inspection unit is incorporated into the printed circuit film bonding unit and the other of the sub-units of the bonding inspection unit is incorporated into the PCB bonding unit.

12. (currently amended) A method of manufacturing a liquid crystal display, the method comprising:

manufacturing a liquid crystal panel assembly;

bonding a printed circuit film on the panel assembly;

~~inspecting the bonding of the printed circuit film on the panel assembly; and~~

bonding a printed circuit board (PCB) to the printed circuit film; and

inspecting the bonding of the printed circuit film on the panel assembly after the bonding of the PCB.

13. (currently amended) The method of claim 12, wherein the inspection is performed before and after the bonding of the PCB.

14. (canceled)

15. (canceled)

16. (original) The method of claim 12, wherein the printed circuit film comprises a tape carrier package.

17. (original) The method of claim 12, wherein the inspection is performed using a differential camera or a differential scope.

18. (original) The method of claim 12, wherein the printed circuit film is bonded on the panel assembly with an anisotropic conductive film (ACF) containing a plurality of conductive particles.

19. (original) The method of claim 18, wherein the bonding of the printed circuit film is performed by thermocompression.

20. (original) The method of claim 19, wherein the inspection detects dents generated by the thermocompression.

21. (new) A system of manufacturing a liquid crystal display, the system comprising:

a panel manufacturing unit for manufacturing a liquid crystal panel assembly including a thin film transistor (TFT) array panel, a color filter array panel, and a liquid crystal layer interposed between the TFT array panel and the color filter array panel;

a printed circuit film bonding unit for bonding a printed circuit film on the panel assembly;

a printed circuit board (PCB) bonding unit for bonding a PCB to the printed circuit film; and

an inspection unit for inspecting strength of bonding of the printed circuit film on the panel assembly.